WHAT IS CLAIMED IS:

1. A module, comprising:

a hermetically-sealable shell having first and second terminal sets;

a first surface acoustic wave (SAW) circuit, located within said shell and couplable to said first terminal set, that filters signals in a first band of communications frequencies; and

a second SAW circuit, located within said shell and couplable to said second terminal set, that filters signals in a second band of communications frequencies.

2. The module as recited in Claim 1 wherein said first band of communications frequencies comprises a frequency between 800 and 900 megahertz.

3. The module as recited in Claim 1 wherein said second band of communications frequencies comprises a frequency between 1800 and 1900 megahertz.

4. The module as recited in Claim 1 wherein said shell comprises a common base that supports said first and second SAW circuits.

5. The module as recited in Claim 1 further comprising a lid coupled to said shell to form a hermetic enclosure that surrounds said first and second SAW circuits.

6. The module as recited in Claim 1 wherein said first and second SAW circuits are located on a common piezoelectric substrate.

7. The module as recited in Claim 6 further comprising a crosstalk shield located between said first and second SAW circuits.

8. A method of manufacturing a circuit module, comprising:

providing a hermetically-sealable shell having first and second terminal sets;

placing a first surface acoustic wave (SAW) circuit in said shell, said first SAW circuit capable of filtering signals in a first band of communications frequencies;

coupling said first SAW circuit to said first terminal set;

placing a second SAW circuit in said shell, said second SAW circuit capable of filtering signals in a second band of communications frequencies;

coupling said second SAW circuit to said second terminal set; and

placing a lid on said shell to form an enclosure that surrounds said first and second SAW circuits.

9. The method as recited in Claim 8 wherein said first band of communications frequencies comprises a frequency between 800 and 900 megahertz.

10. The method as recited in Claim 8 wherein said second band of communications frequencies comprises a frequency between 1800 and 1900 megahertz.

11. The method as recited in Claim 8 wherein said shell comprises a common base that supports said first and second SAW circuits.

12. The method as recited in Claim 8 wherein said enclosure is hermetic.

13. The method as recited in Claim 8 wherein said first and second SAW circuits are located on a common piezoelectric substrate.

14. The method as recited in Claim 13 further comprising forming a crosstalk shield between said first and second SAW circuits.

15. A module, comprising:

a hermetically-sealable shell having first and second terminal sets;

a first surface acoustic wave (SAW) circuit, located within said shell and couplable to said first terminal set, that filters signals in a first band of communications frequencies;

a second SAW circuit, located within said shell and couplable to said second terminal set, that filters signals in a second band of communications frequencies; and

a lid coupled to said shell and forming an enclosure that surrounds said first and second SAW circuits.

16. The module as recited in Claim 15 wherein said first band of communications frequencies comprises a frequency between 800 and 900 megahertz.

17. The module as recited in Claim 15 wherein said second band of communications frequencies comprises a frequency between 1800 and 1900 megahertz.

18. The module as recited in Claim 15 wherein said shell comprises a common base that supports said first and second SAW circuits.

19. The module as recited in Claim 15 wherein said enclosure is hermetic.

20. The module as recited in Claim 15 wherein said first and second SAW circuits are located on a common piezoelectric substrate.

21. The module as recited in Claim 20 wherein a crosstalk shield is located between said first and second SAW circuits.